General Description

The MAX15008 features a 300mA LDO regulator, a voltage tracker, and an overvoltage protection (OVP) controller to protect downstream circuits from highvoltage transients. The MAX15010 includes only the 300mA LDO voltage regulator and voltage tracker. Both devices operate over a wide 5V to 40V supply voltage range and are able to withstand load-dump transients up to 45V. The MAX15008/MAX15010 feature short-circuit and thermal-shutdown protection.

The 300mA LDO regulator consumes less than 67µA quiescent current at light loads and is well suited to power always-on circuits during "key off" conditions. The LDO features independent enable and hold inputs, as well as a microprocessor (µP) reset output with an adjustable reset timeout period.

The voltage tracker accurately (±3mV) tracks a voltage applied to its input from either the LDO output or an external source. It can supply up to 50mA of current to a remote sensor, allowing for precise ratiometric tracking in industrial applications. A separate enable input turns the tracker on or off, reducing supply current when the tracker is unused. The voltage tracker also features protection against battery reversal, an output short circuit to the battery, or an output voltage excursion below ground potential to as much as -5V.

The MAX15008 OVP controller operates with an external enhancement mode n-channel MOSFET. While the monitored voltage remains below the adjustable threshold, the MOSFET stays on. When the monitored voltage exceeds the OVP threshold, the OVP controller quickly turns off the external MOSFET. The OVP controller is configurable as a load-disconnect switch or a voltage limiter.

The MAX15008/MAX15010 are available in a thermally enhanced, 32-pin (5mm x 5mm) TQFN package and are fully specified over the -40°C to +125°C operating temperature range.

Applications

• Multimedia Power Supply

Features

- 300mA LDO Regulator, Voltage Tracker, and OVP Controller (MAX15008)
- 300mA LDO Regulator and Voltage Tracker (MAX15010)
- 50mA Voltage Tracker with ±3mV Tracking Accuracy
- 5V to 40V Wide Operating Supply Voltage Range
- 67µA Quiescent Current LDO Regulator
- OVP Controller Disconnects or Limits Output from Battery Overvoltage Conditions (MAX15008)
- LDO Regulator with Enable, Hold, and Reset Features

Ordering Information

*+Denotes a lead(Pb)-free/RoHS-compliant package. *EP = Exposed pad.*

Selector Guide

Pin Configurations

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect
device reliability.

Electrical Characteristics

 $(V_{IN} = V_{TRACK} = +14V$, $V_{SGND} = V_{PGND} = 0V$, $C_{GATE} = 6000pF$, $C_{IN} = 10\mu F$ (ESR $\leq 1.5\Omega$), C_{OUT} LDO = 22µF (ceramic), $C_{TRACK} =$ 3.3μF (ceramic) (ESR ≤ 1.5Ω), C_{OUT_TRK} = 10μF (ESR ≤ 1.5Ω), C_{REF} = 1000pF, V_{OUT_LDO} = 5V, T_A = T_J = -40°C to +125°C, unless otherwise noted. Typical values are $\overline{at} T_A = +25^{\circ}C$.) (Note 1)

Electrical Characteristics (continued)

 $(V_{IN} = V_{TRACK} = +14V, V_{SGND} = V_{PGND} = 0V, C_{GATE} = 6000pF, C_{IN} = 10\mu F (ESR \le 1.5\Omega), C_{OUT_LDO} = 22\mu F (ceramic), C_{TRACK} = 0.000pF, C_{IN} = 10\mu F (ESR \le 1.5\Omega)$ 3.3μF (ceramic) (ESR ≤ 1.5Ω), C_{OUT_TRK} = 10μF (ESR ≤ 1.5Ω), C_{REF} = 1000pF, V_{OUT_LDO} = 5V, T_A = T_J = -40°C to +125°C, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

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Electrical Characteristics (continued)

 $(V_{IN} = V_{TRACK} = +14V, V_{SGND} = V_{PGND} = 0V, C_{GATE} = 6000pF, C_{IN} = 10\mu F (ESR \le 1.5\Omega), C_{OUT_LDO} = 22\mu F (ceramic), C_{TRACK} = 0.000pF, C_{IN} = 10\mu F (ESR \le 1.5\Omega)$ 3.3μF (ceramic) (ESR ≤ 1.5Ω), C_{OUT_TRK} = 10μF (ESR ≤ 1.5Ω), C_{REF} = 1000pF, V_{OUT_LDO} = 5V, T_A = T_J = -40°C to +125°C, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

Electrical Characteristics (continued)

 $(V_{IN} = V_{TRACK} = +14V, V_{SGND} = V_{PGND} = 0V, C_{GATE} = 6000pF, C_{IN} = 10\mu F (ESR \le 1.5\Omega), C_{OUT LDO} = 22\mu F (ceramic), C_{TRACK} = 1.5\Omega$ 3.3μF (ceramic) (ESR ≤ 1.5Ω), C_{OUT_TRK} = 10μF (ESR ≤ 1.5Ω), C_{REF} = 1000pF, V_{OUT_LDO} = 5V, T_A = T_J = -40°C to +125°C, unless otherwise noted. Typical values are $a\overline{t}$ T_A = +25°C.) (Note 1)

Note 1: Limits to -40°C are guaranteed by design.

Note 2: 1.8V is the minimum limit for proper HOLD functionality.

Note 3: Dropout is defined as V_{IN} - V_{OUTLDO} when V_{OUTLDO} is 98% of the value of V_{OUTLDO} for V_{IN} = V_{OUTLDO} + 1.5V.

Note 4: Maximum output current may be limited by the power dissipation of the package.

Typical Operating Characteristics

(VIN = VEN_ = +14V, CIN = 10µF, COUT_LDO = 22µF, CTRACK = COUT_TRK = 10µF, VOUT_LDO = 5V, FB_LDO = SGND, TA = +25°C, unless otherwise specified.)

TEMPERATURE (°C)

 $V_{IN} (V)$

Typical Operating Characteristics (continued)

(VIN = VEN_ = +14V, CIN = 10µF, COUT_LDO = 22µF, CTRACK = COUT_TRK = 10µF, VOUT_LDO = 5V, FB_LDO = SGND, TA = +25°C, unless otherwise specified.)

Typical Operating Characteristics (continued)

(VIN = VEN_ = +14V, CIN = 10µF, COUT_LDO = 22µF, CTRACK = COUT_TRK = 10µF, VOUT_LDO = 5V, FB_LDO = SGND, TA = +25°C, unless otherwise specified.)

Typical Operating Characteristics (continued)

(VIN = VEN_ = +14V, CIN = 10µF, COUT_LDO = 22µF, CTRACK = COUT_TRK = 10µF, VOUT_LDO = 5V, FB_LDO = SGND, TA = +25°C, unless otherwise specified.)

TEMPERATURE (°C)

Pin Description

Pin Description (continued)

Functional Diagram

Detailed Description

The MAX15008/MAX15010 integrate a 300mA LDO voltage regulator, a voltage tracker, and an OVP controller. These devices operate over a wide 5V to 40V supply voltage range and are able to withstand voltage transients up to 45V.

The MAX15008/MAX15010 feature a 300mA LDO regulator that consumes less than 70µA of current under light-load conditions and feature a fixed 5V or an adjustable output voltage (1.8V to 11V). Connect FB_LDO to ground to select a fixed 5V output voltage, or select the LDO output voltage by connecting an external resistive voltage-divider at FB_LDO. The regulator sources at least 300mA of current and includes a current limit of 330mA (min). Enable the LDO by pulling EN_LDO high.

The tracker can be powered from the LDO input supply voltage or an independent voltage source. It is designed to supply power to a remote sensor and is able to handle the severe conditions in industrial applications. Set the tracker output voltage by connecting a resistive voltagedivider to OUT_TRK and connecting ADJ to the tracking source. The tracker feedback (FB_TRK) and a separate tracker reference voltage input (ADJ) offer the flexibility of setting the tracker output to be lower, equal to, or higher than the main (LDO) output. Pull EN_TRK to SGND to turn the tracker off and keep the device in always-on, lowquiescent-current operation.

The OVP controller (MAX15008 only) relies on an external MOSFET with adequate voltage rating (V_{DSS}) to protect downstream circuitry from overvoltage transients. The OVP controller drives the gate of the external n-channel MOSFET, and is configurable to operate as an overvoltage protection switch or as a closed-loop voltage limiter.

GATE Voltage (MAX15008 Only)

The MAX15008 uses a high-efficiency charge pump to generate the GATE voltage for the external n-channel MOSFET. Once the input voltage $(V_{\vert N})$ exceeds the undervoltage-lockout (UVLO) threshold, the internal charge pump fully enhances the external n-channel MOSFET. An overvoltage condition occurs when the voltage at FB_PROT goes above the threshold voltage (V_{TH} PROT). After V_{TH} PROT is exceeded, GATE is quickly pulled to PGND with a 63mA pulldown current. The MAX15008 includes an internal clamp from GATE to SOURCE that ensures that the voltage at GATE never exceeds one diode drop below SOURCE during gate discharge. The voltage clamp also prevents the GATE-to-SOURCE voltage from exceeding the absolute maximum rating for the V_{GS} of the external MOSFET in case the source terminal is accidentally shorted to 0V.

Overvoltage Monitoring (MAX15008 Only)

The OVP controller monitors the voltage at FB_PROT and controls an external n-channel MOSFET, isolating, or limiting the load during an overvoltage condition. Operation in OVP switch mode or limiter mode depends on the connection between FB_PROT and the external MOSFET.

Overvoltage Switch Mode

When operating in OVP switch mode, the FB_PROT divider is connected to the drain of the external MOSFET. The feedback path consists of the voltage-divider tapped at FB_PROT, FB_PROT's internal comparator, the internal gate-charge pump/gate pulldown, and the external n-channel MOSFET (Figure 1). When the programmed overvoltage threshold is exceeded, the internal comparator quickly pulls GATE to ground and turns off the external MOSFET, disconnecting the power source from the load. In this configuration, the voltage at the source of the MOSFET is not monitored. When the voltage at FB PROT decreases below the overvoltage threshold, the MAX15008 raises the voltage at GATE, reconnecting the load to the power source.

Figure 1. Overvoltage Switch Configuration (MAX15008)

Overvoltage-Limiter Mode

When operating in overvoltage-limiter mode, the feedback path consists of SOURCE, FB_PROT's internal comparator, the internal-gate charge pump/gate pulldown, and the external n-channel MOSFET (Figure 2). This configuration results in the external MOSFET operating as a hysteretic voltage regulator.

During normal operation, GATE is enhanced 8.1V above V_{IN} . The external MOSFET source voltage is monitored through a resistive voltage-divider between SOURCE and FB_PROT. When V_{SOURCE} exceeds the adjustable overvoltage threshold, an internal pulldown switch discharges the gate voltage and quickly turns the MOSFET off. Consequently, the source voltage begins to fall. The $V_{SOLIRCF}$ fall time is dependent on the MOSFET's gate charge, the internal charge-pump current, the output load, and any load capacitance at SOURCE. When the voltage at FB_PROT is below the overvoltage threshold by an amount equal to the hysteresis, the charge pump restarts and turns the MOSFET back on. In this way, the OVP controller attempts to regulate VSOURCE around the overvoltage threshold. SOURCE remains high during overvoltage transients and the MOSFET continues to conduct during an overvoltage event. The hysteresis of the FB_PROT comparator and the gate turn-on delay force the external MOSFET to operate in a switched on/off sequence during an overvoltage event.

Exercise caution when operating the MAX15008 in voltage-limiting mode for long durations. Care must be taken against prolonged or repeated exposure to overvoltage events while delivering large amounts of load current as the power dissipation in the external MOSFET may be high under these conditions. To prevent damage to the MOSFET, implement proper heatsinking. The capacitor connected between SOURCE and ground can also be damaged if the ripple current rating for the capacitor is exceeded.

As the transient voltage decreases, the voltage at SOURCE falls. For fast-rising transients and very large MOSFETs, connect an additional capacitor from GATE to

Figure 2. Overvoltage Limiter (MAX15008)

PGND. This capacitor acts as a voltage-divider working against the MOSFET's drain-to-gate capacitance. If using a very low gate-charge MOSFET, additional capacitance from GATE to ground might be required to reduce the switching frequency.

Control Logic

The MAX15008/MAX15010 LDO features two logic inputs (EN_LDO and HOLD), making these devices suitable for industrial applications. For example, when the ignition key signal drives EN_LDO high, the regulator turns on and remains on even if EN_LDO goes low, as long as HOLD is forced low and stays low after initial regulator power-up. In this state, releasing HOLD turns the regulator output (OUT_LDO) off. This feature makes it possible to implement a self-holding circuit without external components. Forcing EN_LDO low and HOLD high (or unconnected) places the regulator into shutdown mode, reducing the supply current to less than 16µA. Table 1 shows the state of OUT_LDO with respect to EN_LDO and HOLD. Leave HOLD unconnected or connect directly to OUT_LDO to allow the EN_LDO input to act as a standard on/off logic input for the regulator.

Table 1. EN_LDO/HOLD Truth Table/State Table

Applications Information

Setting the Output Voltage

The MAX15008/MAX15010 feature dual-mode operation: these devices operate in either a preset voltage mode or an adjustable mode. In preset voltage mode, internal feedback resistors set the linear regulator output voltage ($V_{\text{OUT LDO}}$) to 5V. To select the preset 5V output voltage, connect FB_LDO to SGND.

To select an adjustable output voltage between 1.8V and 11V, use two external resistors connected as a voltagedivider to FB_LDO (Figure 3). Set the output voltage using the following equation:

VOUT LDO = VFB LDO x $(R_1 + R_2)/R_2$

where $V_{FB \text{ LDO}}$ = 1.235V and R₂ ≤ 50kΩ.

Figure 3. Setting the LDO Output Voltage

Setting the RESET Timeout Period

The RESET timeout period is adjustable to accommodate a variety of applications. Set the RESET timeout period by connecting a capacitor (CRESET), between CT and SGND. Use the following formula to select the reset timeout period (tRESET):

tRESET = CRESET x VCT_TH/ICT

where t RESET is in seconds and CRESET is in μ F. V_{CT} TH is the CT ramp threshold in volts and I_{CT} is the CT ramp current in µA, as described in the *Electrical Characteristics* table.

Leave CT open to select an internally fixed timeout period of 10µs. To maintain reset timeout accuracy, use a lowleakage (< 10nA) type capacitor.

Tracker Input/Feedback Adjustment

The tracker can be powered from the LDO input supply voltage or an independent voltage source. It is designed to supply power to a remote sensor and its supply input (TRACK) and is able to handle the severe conditions in industrial applications such as battery reversal and loaddump transients up to 45V.

The tracker feedback (FB_TRK) and a separate tracker reference voltage input (ADJ) offer the flexibility of setting the tracker output to be lower, equal to, or higher than the main (LDO) output. Other external voltages can also be tracked.

Connect ADJ to OUT_LDO and FB_TRK to OUT_TRK to track the LDO output voltage directly (Figure 4a). To track a voltage higher than $V_{\Omega U}T_{\Omega O}$, directly connect ADJ to OUT_LDO and connect FB_TRK to OUT_TRK through a resistive voltage-divider (Figure 4b). To track a voltage lower than the LDO regulator output $(V_{\OmegaUT+D}\Omega)$, directly connect FB_TRK to OUT_TRK and connect ADJ to OUT_LDO through a resistive voltage-divider (Figure 4c). To track an external voltage (V_X) with a generic attenuation/amplification ratio, connect resistive voltage-dividers between ADJ and the voltage input or output to be tracked (V_X) , and between OUT TRK and FB TRK (Figure 4d). Pay attention to the resistive loading of the voltage V_X due to the divider R5 and R6.

To track the internal REF voltage (1.235V), directly, connect ADJ to REF. The voltage at FB_TRK or ADJ should be greater than or equal to 1.1V and less than V_{TRACK} -0.5V. Resistors should have a tolerance of 1% or better. Their values should be low enough to ensure that the divider current is at least 100x the maximum input bias current at pins FB_TRK and ADJ (I_{FB} TRK ADJ, max = 0.2 μ A).

Figure 4. Tracker Input and Feedback Adjustment

Setting the Overvoltage Threshold (MAX15008 Only)

The MAX15008 provides an accurate means to set the overvoltage threshold for the OVP controller using FB_PROT. Use a resistive voltage-divider to set the desired overvoltage threshold (Figure 5). FB_PROT has a rising 1.235V threshold with a 4% falling hysteresis.

Begin by selecting the total end-to-end resistance, R_{TOTAL} $=$ R₅ + R₆. Choose R_{TOTAL} to yield a total current equivalent to a minimum of 100 x I_{FB} $PROT$ (FB_PROT's input maximum bias current) at the desired overvoltage threshold. See the *Electrical Characteristics* table.

For example:

With an overvoltage threshold (V_{OV}) set to 20V, R_{TOTAL} < 20V/(100 x IFB_PROT), where IFB_PROT is FB_PROT's maximum 100nA bias current:

RTOTAL < 2MΩ

Use the following formula to calculate $R₆$:

 R_6 = V TH_PROT x RTOTAL/VOV

where V_{TH} PROT is the 1.235V FB PROT rising threshold and $V_{\text{O}V}$ is the desired overvoltage threshold. $R₆$ = 124kΩ:

$$
R_{\text{TOTAL}} = R_5 + R_6
$$

where R₅ = 1.88MΩ. Use a standard 1.87MΩ resistor.

A lower value for total resistance dissipates more power, but provides better accuracy and robustness against external disturbances.

Input Transients Clamping

When the external MOSFET is turned off during an overvoltage event, stray inductance in the power path may cause additional input-voltage spikes that exceed the V_{DSS} rating of the external MOSFET or the absolute maximum rating for the MAX15008 (IN, TRACK). Minimize stray inductance in the power path using wide traces and minimize the loop area included by the power traces and the return ground path.

For further protection, add a zener diode or transient voltage suppressor (TVS) rated below the absolute maximum rating limits (Figure 6).

Figure 6. Protecting the MAX15008 Input from High-Voltage Transients

Figure 5. Setting the Overvoltage Threshold (MAX15008)

External MOSFET Selection

Select the external MOSFET with adequate voltage rating (V_{DSS}) to withstand the maximum expected loaddump input voltage. The on-resistance of the MOSFET (RDS(ON)) should be low enough to maintain a minimal voltage drop at full load, limiting the power dissipation of the MOSFET.

During regular operation, the power dissipated by the MOSFET is:

$P_{NORMAL} = I_{LOAD}2 \times R_{DS(ON)}$

Normally, this power loss is small and is safely handled by the MOSFET. However, when operating the MAX15008 in overvoltage-limiter mode under prolonged or frequent overvoltage events, select an external MOSFET with an appropriate power rating.

During an overvoltage event, the power dissipation in the external MOSFET is proportional to both load current and to the drain-source voltage, resulting in high power dissipated in the MOSFET (Figure 7). The power dissipated across the MOSFET is:

POV_LIMITER $=$ VQ1 x I _{LOAD}

where V_{Q1} is the voltage across the MOSFET's drain and source during overvoltage-limiter operation, and I_{LOD} is the load current.

Overvoltage-Limiter Mode Switching Frequency

When the MAX15008 is configured in overvoltagelimiter mode, the external n-channel MOSFET is

Figure 7. Power Dissipated Across MOSFETs During an Overvoltage Fault (Overvoltage-Limiter Mode)

subsequently switched on and off during an overvoltage event. The output voltage at SOURCE resembles a periodic sawtooth waveform. Calculate the period of the waveform (t_{OVP}) by summing three time intervals (Figure 8):

$$
t_{OVP} = t_1 + t_2 + t_3
$$

where t_1 is the V_{SOLRCE} output discharge time, t_2 is the GATE delay time, and t_3 is the $V_{SOLIRCF}$ output charge time.

During an overvoltage event, the power dissipated inside the MAX15008 is due to the gate pulldown current (IGATEPD). This amount of power dissipation is worse when $I_{\text{SOLRCE}} = 0$ (C_{SOURCE} is discharged only by the internal current sink).

The worst-case internal power dissipation contribution in overvoltage-limiter mode (P_{OVP}) in watts can be approximated using the following equation:

$$
P_{OVP} = V_{OV} \times 0.98 \times I_{GATEPD} \times \frac{t_1}{t_{OVP}}
$$

where V_{OV} is the overvoltage-threshold voltage in volts and IGATEPD is the 63mA (typ) GATE pulldown current.

Output Discharge Time (t1)

When the voltage at SOURCE exceeds the adjusted overvoltage threshold, GATE's internal pulldown is enabled until VSOURCE drops by 4%. The internal current sink (I_{GATEPD}) and the external load current (I_{LOAD}), discharge the external capacitance from SOURCE to ground.

Figure 8. MAX15008 Timing Diagram

Calculate the discharge time (t_1) using the following equation:

$$
t_1 = C_{\text{SOURCE}} \times \frac{0.04 \times V_{\text{OV}}}{I_{\text{LOAD}} + I_{\text{GATEPD}}}
$$

where t_1 is in ms, V_{OV} is the adjusted overvoltage threshold in volts, I_{LOAD} is the external load current in mA, and IGATEPD is the 63mA (typ) internal pulldown current of GATE. CSOURCE is the value of the capacitor connected between the source of the MOSFET and PGND in µF.

GATE Delay Time (t2)

When SOURCE falls 4% below the overvoltage threshold voltage, the internal current sink is disabled and the internal charge pump begins recharging the external GATE voltage. Due to the external load, the SOURCE voltage continues to drop until the gate of the MOSFET is recharged. The time needed to recharge GATE and reenhance the external MOSFET is approximately:

$$
t_2 = C_{iss} \times \frac{V_{GS(TH)} + V_F}{I_{GATE}}
$$

where t_2 is in μs , C_{iss} is the input capacitance of the MOSFET in pF, and $V_{\text{GS}(TH)}$ is the gate-to-source threshold voltage of the MOSFET in volts. V_F is the 0.7V (typ) internal clamp-diode forward voltage of the MOSFET in volts, and I_{GATF} is the charge-pump current, 45 μ A (typ). Any external capacitance between GATE and PGND adds up to C_{iss} .

During t_2 , the SOURCE capacitance (C_{SOURCE}) loses charge through the output load. The voltage across C_{SOURCE} decreases by ∆V₂ until the MOSFET reaches its V_{GS(TH)} threshold. Approximate ΔV_2 using the following formula:

$$
\Delta V_2 = \frac{I_{LOAD} \times t_2}{C_{SOURCE}}
$$

SOURCE Output Charge Time (t3)

Once the GATE voltage exceeds the gate-to-source threshold $(V_{\text{GS}(TH)})$ of the external MOSFET, the MOSFET turns on and the charge through the internal charge pump with respect to the drain potential (Q_G) determines the slope of the output-voltage rise. The time required for the SOURCE voltage to rise again to the overvoltage threshold is:

$$
t_3 = \frac{C_{rss} \times \Delta V_{SOLRCE}}{I_{GATE}}
$$

where $\Delta V_{\text{SOLIRCF}}$ = (V_{OV} x 0.04) + ΔV_2 in volts, and C_{rss} is the MOSFET's reverse-transfer capacitance in pF. Any external capacitance between GATE and PGND adds up to C_{rss}.

Power Dissipation/Junction Temperature

During normal operation, the MAX15008/MAX15010 have two main sources of internal power dissipation: the LDO and the voltage tracker.

Calculate the power dissipation due to the LDO as:

$$
P_{LDO} = (V_{IN} - V_{OUT_LDO}) \times I_{OUT_LDO}
$$

where V_{IN} is the LDO input supply voltage in volts, V_{OUT LDO} is the output voltage of the LDO in volts, and I_{OUT} I_{DO} is the LDO total load current in mA.

Calculate power dissipation due to the tracker as:

PTRK = (VTRACK - VOUT_TRK) x IOUT_TRK

where V_{TRACK} is the tracker input-supply voltage in volts, VOUT TRK is the output voltage of the tracker in volts, and IOUT TRK is the tracker load current in mA.

The total power dissipation P_{DISS} in mW as:

PDISS = PLDO + PTRK

For prolonged exposure to overvoltage events, use the V_{IN} and V_{TRACK} voltages expected during overvoltage conditions. Under these circumstances, the corresponding internal power-dissipation contribution (POVP) calculated in the *Overvoltage-Limiter Mode Switching Frequency* section should also be included in the total power dissipation (P_{DISS}).

For a given ambient temperature (T_A) , calculate the junction temperature (T_J) as follows:

$$
T_J = T_A + P_{DISS} \times \theta_{JA}
$$

where T_J and T_A are in °C and θ_{JA} is the junction-toambient thermal resistance in °C/W, as listed in the *Absolute Maximum Ratings* section.

The junction temperature should never exceed +150°C during normal operation.

Thermal Protection

When the junction temperature exceeds $T_J = +160^{\circ}C$, the MAX15008/MAX15010 shut down to allow the device to cool. When the junction temperature drops to +140°C, the thermal sensor turns all enabled blocks on again, resulting in a cycled output during continuous thermal-overload conditions. Thermal protection protects the MAX15008/ MAX15010 from excessive power dissipation. For continuous operation, do not exceed the absolute maximum junction temperature rating of +150°C.

Typical Operating Circuits

Pin Configurations (continued) Chip Information

PROCESS: BiCMOS

Package Information

For the latest package outline information and land patterns (footprints), go to **www.maximintegrated.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Revision History

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim Integrated's website at www.maximintegrated.com.

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